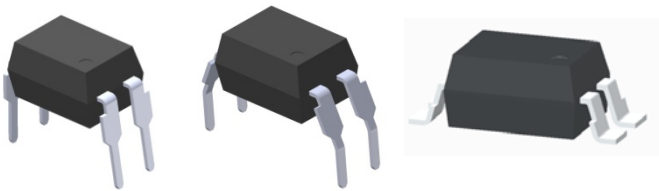
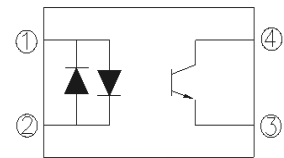


4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER AC INPUT PHOTOCOUPLER EL814 Series



Schematic



Pin Configuration

1. Anode / Cathode
2. Cathode / Anode
3. Emitter
4. Collector

Features

- Compliance Halogens Free
(Br < 900 ppm, Cl < 900 ppm, Br+Cl < 1500 ppm)
- AC input response
- Current transfer ratio (CTR: Min. 20% at $I_F = \pm 1\text{mA}$, $V_{CE} = 5\text{V}$)
- High isolation voltage between input and output (Viso = 5000 V rms)
- Wide Operating temperature range -55~110°C
- High collector-emitter voltage $V_{CEO} = 80\text{V}$
- Compact dual-in-line package
- Pb free
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL and cUL approved
- VDE approved
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

Description

The EL814 Series of devices each consist of two infrared emitting diodes, connected in inverse parallel, optically coupled to a phototransistor detector. They are packaged in a 4-pin DIP package and available in side-lead spacing and SMD option.

Applications

- AC line monitor
- Programmable controllers
- Telephone line interface
- Unknown polarity DC sensor

Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward Current	I _F	±50	mA
	Peak Forward Current (t = 10μs)	I _{FM}	1	A
	Power dissipation	P _D	100	mW
Output	Power dissipation	P _C	150	mW
	Collector current	I _C	50	mA
	Collector-Emitter voltage	V _{CEO}	80	V
	Emitter-Collector voltage	V _{ECO}	6	V
Total Power Dissipation		P _{TOT}	200	mW
Isolation Voltage*1		V _{ISO}	5000	V rms
Operating Temperature		T _{OPR}	-55 to 110	°C
Storage Temperature		T _{STG}	-55 to 125	°C
Soldering Temperature*2		T _{SOL}	260	°C

Notes

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

*2 For 10 seconds

Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V_F	-	1.2	1.4	V	$I_F = \pm 20\text{mA}$
Input capacitance	C_{in}	-	50	250	pF	$V = 0, f = 1\text{KHz}$

Output

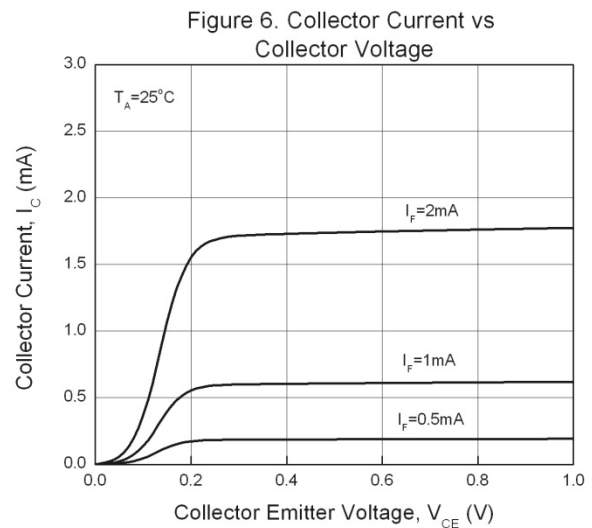
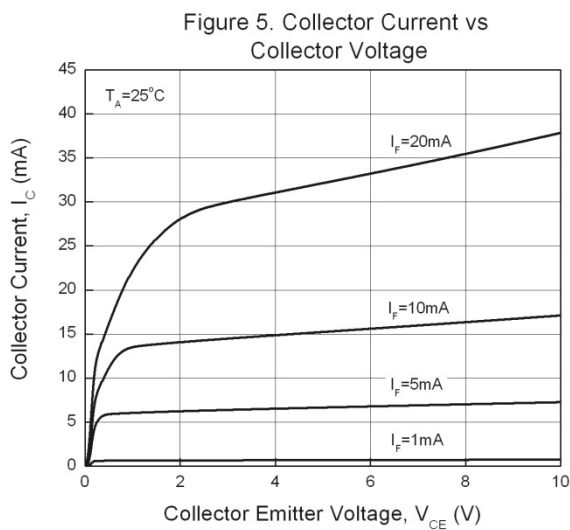
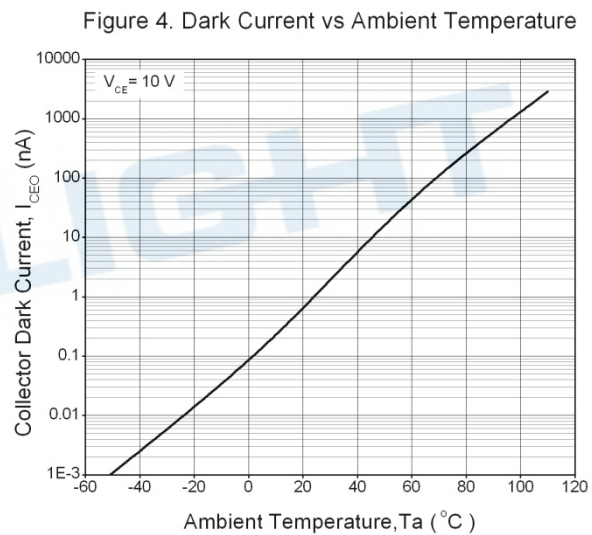
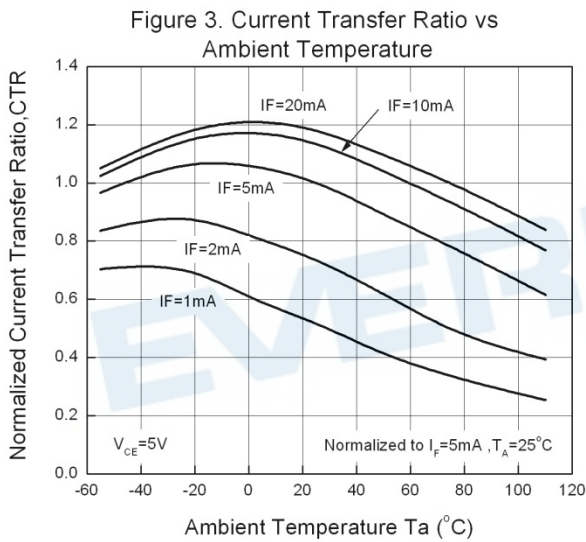
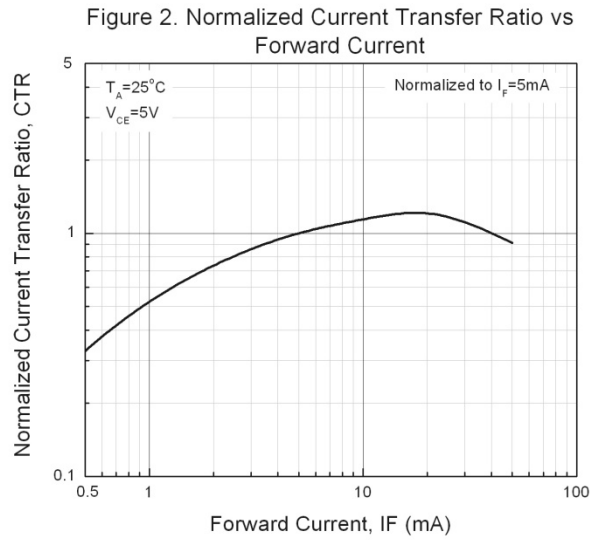
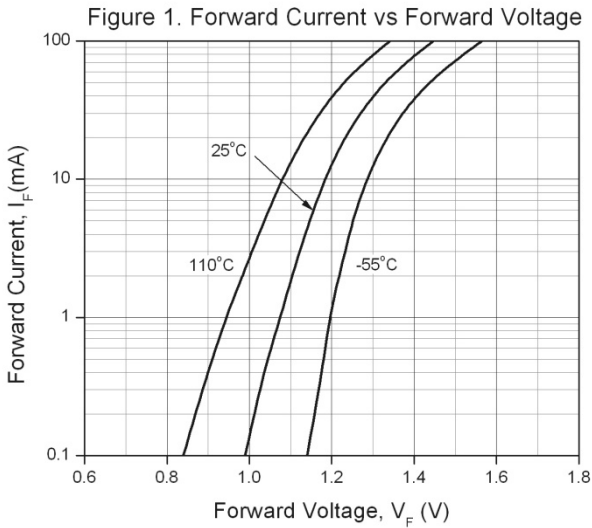
Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	I_{CEO}	-	-	100	nA	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$
Collector-Emitter breakdown voltage	BV_{CEO}	80	-	-	V	$I_C = 0.1\text{mA}$
Emitter-Collector breakdown voltage	BV_{ECO}	6	-	-	V	$I_E = 0.1\text{mA}$

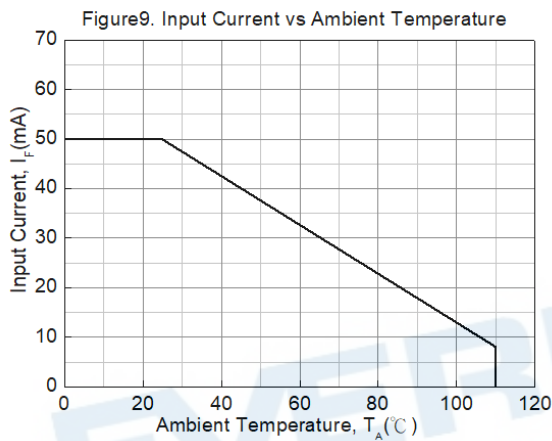
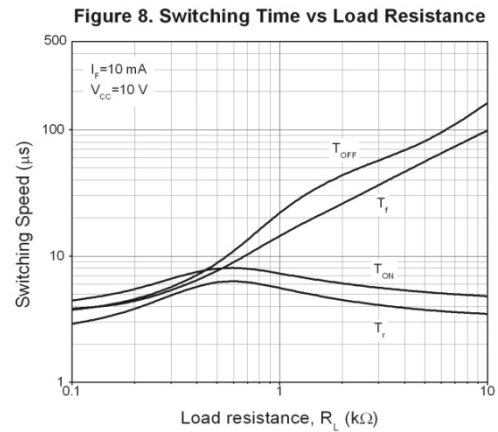
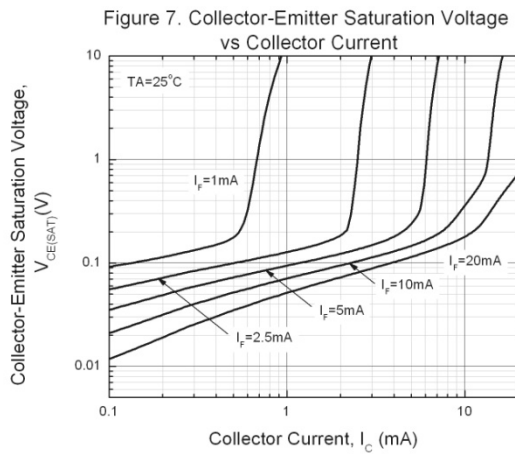
Transfer Characteristics

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	EL814	20	-	300	%	$I_F = \pm 1\text{mA}, V_{CE} = 5\text{V}$
	EL814A	50	-	150		
Collector current	EL814	0.2	-	3	mA	$I_F = \pm 1\text{mA}, V_{CE} = 5\text{V}$
	EL814A	0.5	-	1.5		
CTR Symmetry		0.5	-	2.0	-	$I_F = \pm 1\text{mA}, V_{CE} = 5\text{V}$
Collector-emitter saturation voltage	$V_{CE(sat)}$	-	0.05	0.2	V	$I_F = \pm 20\text{mA}, I_C = 1\text{mA}$
Isolation resistance	R_{IO}	5×10^{10}	10^{11}	-	Ω	$V_{IO} = 500\text{Vdc}, 40\sim 60\%R.H$
Cut-off frequency	f_c	-	80	-	kHz	$V_{CE}=5\text{V}, I_C=2\text{mA}, R_L=100\Omega, -3\text{dB}$
Floating capacitance	C_{IO}	-	0.6	1.0	pF	$V_{IO} = 0, f = 1\text{MHz}$
Rise time	T_r	-	-	18	μs	$V_{CE}=2\text{V}, I_C=2\text{mA}, R_L=100\Omega$
Fall time	T_f	-	-	18	μs	

* Typical values at $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves





Note: The graphs shown in this datasheet are representing typical data only and do not show guaranteed values

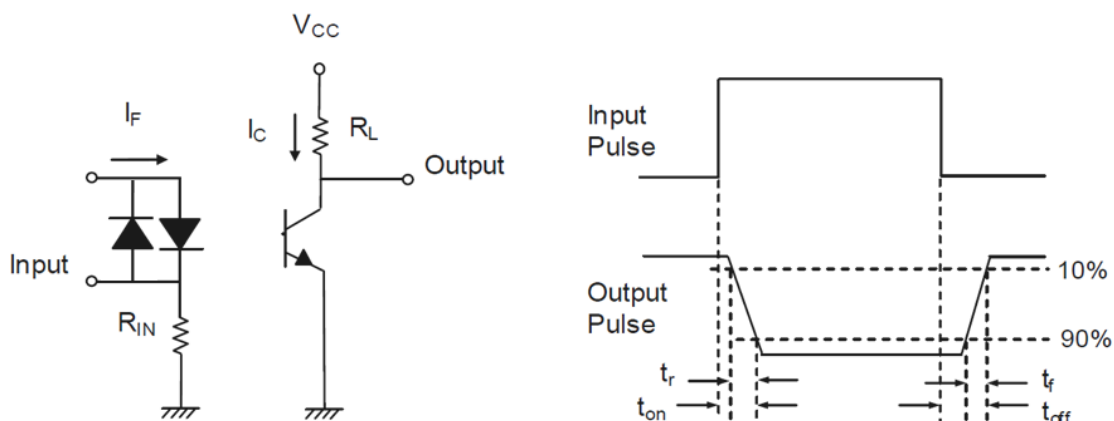


Figure 10. Switching Time Test Circuit & Waveforms

Order Information

Part Number

EL814X(Y)(Z)-V

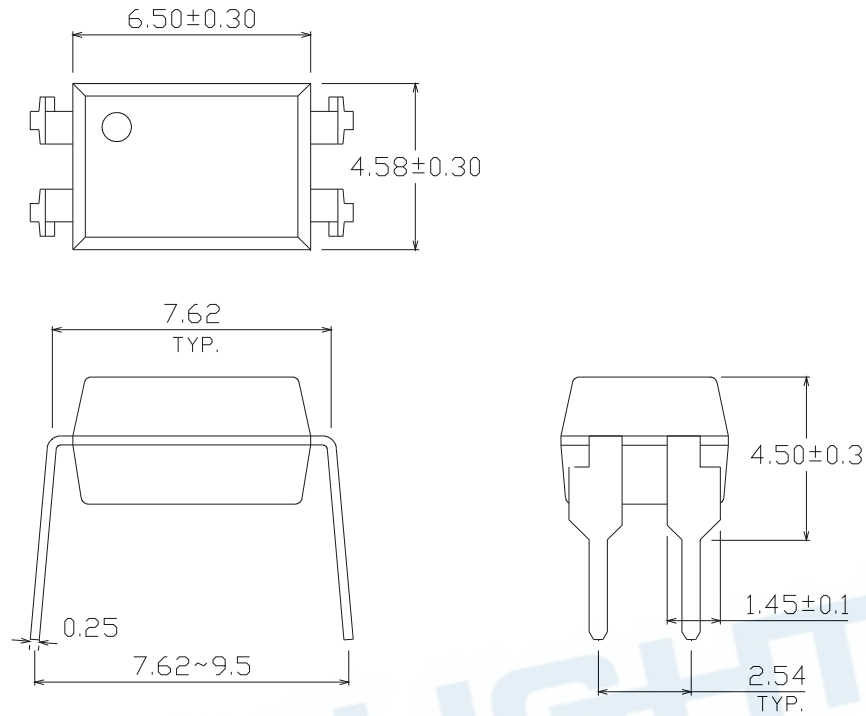
Notes

- X = Lead form option (S, S1, M or none)
- Y = CTR Rank (A or none)
- Z = Tape and reel option (TA, TB, TU, TD or none)
- V = VDE safety (optional)

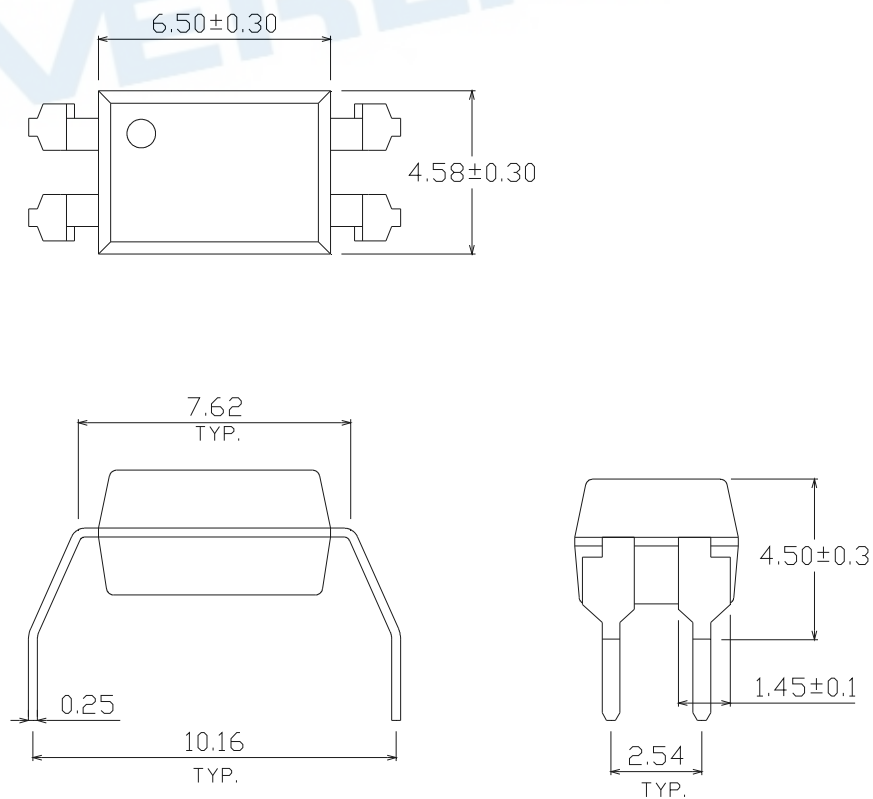
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel
S (TU)	Surface mount lead form + TU tape & reel option	1500 units per reel
S (TD)	Surface mount lead form + TD tape & reel option	1500 units per reel
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	2000 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	2000 units per reel

Package Dimension (Dimensions in mm)

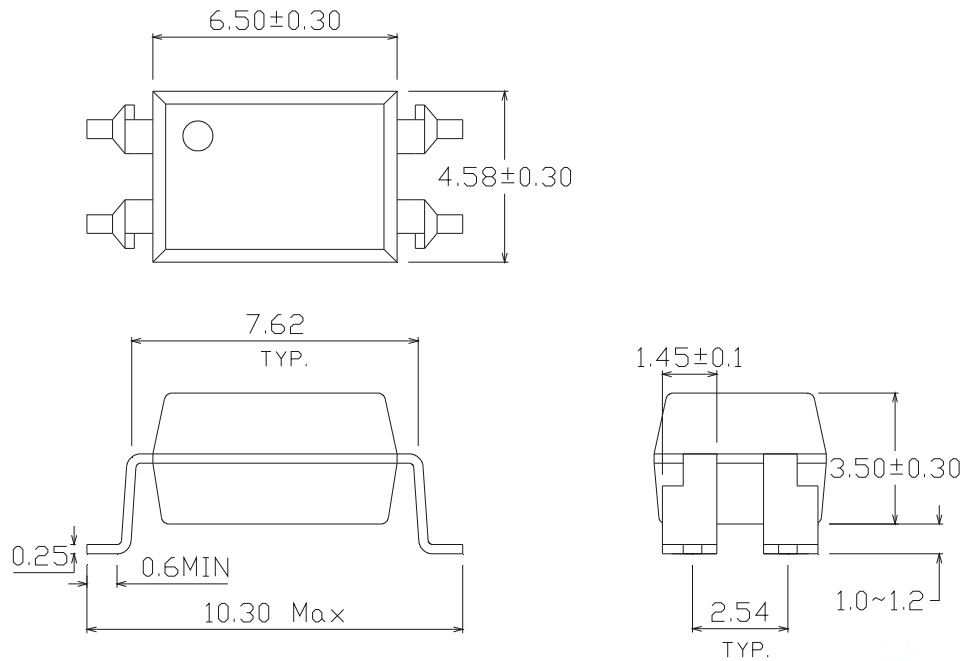
Standard DIP Type



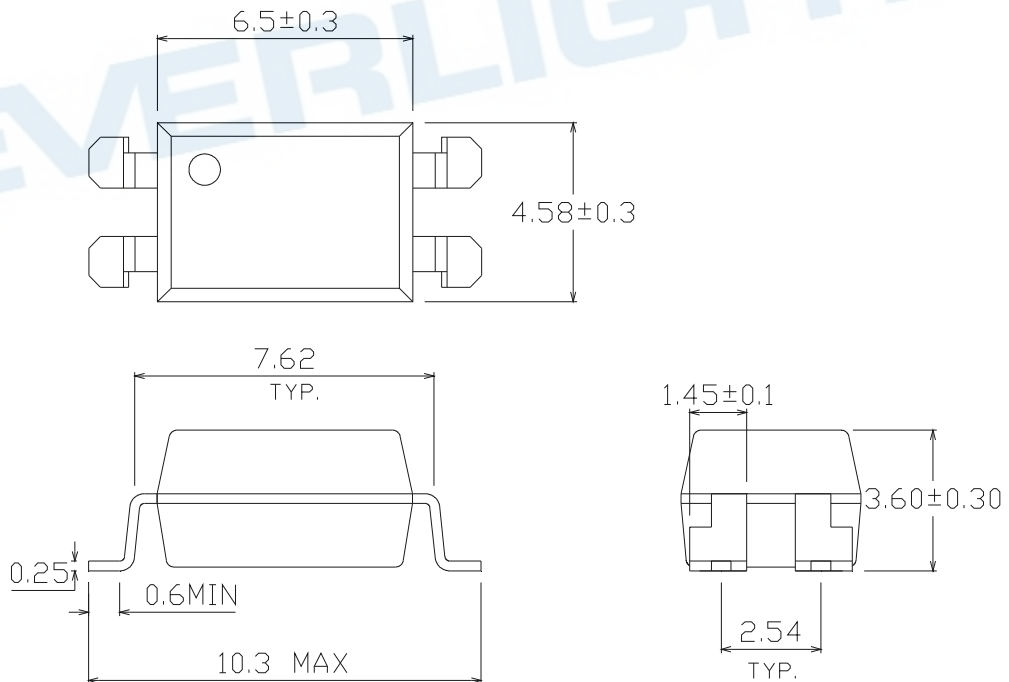
Option M Type



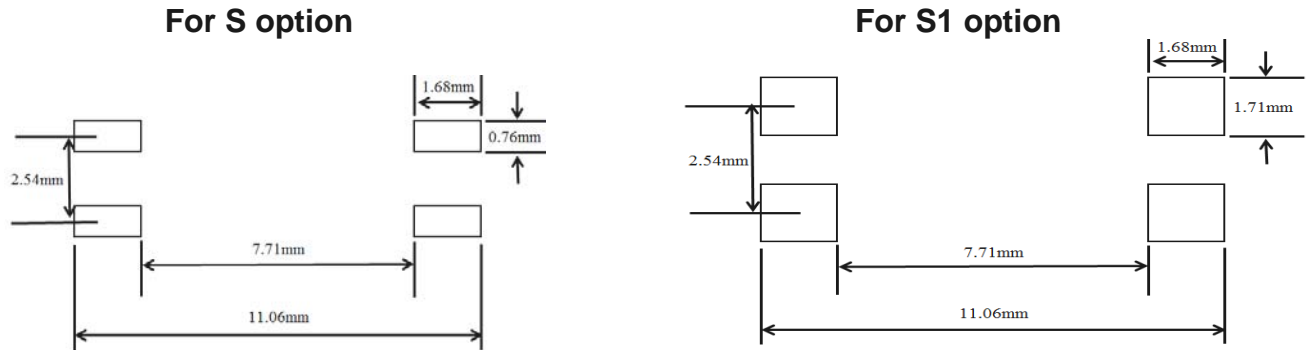
Option S Type



Option S1 Type



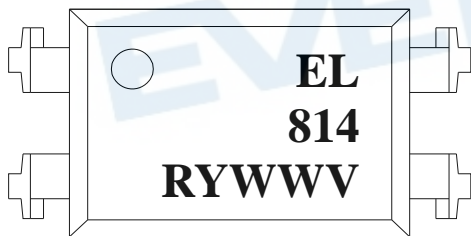
Recommended pad layout for surface mount leadform



Notes

Suggested pad dimension is just for reference only.
 Please modify the pad dimension based on individual need.


Device Marking





Notes

- EL denotes EVERLIGHT
- 814 denotes Device Number
- R denotes CTR Rank (A or none)
- Y denotes 1 digit Year code
- WW denotes 2 digit Week code
- V denotes VDE (optional)

Label form


EVERLIGHT
11 → 月份


客戶料號 ← CPN: XXXXXXXXXXXX 測試區
  → RoHS標示

億光料號 ← P/N: XXXXXXXXXXXX
  → 安規標示

億光品名 ← EL817M(C)-VG
 QTY: 000000 → 包裝數量

生產周別 ← D/C: YWWX CAT: X REF: XXXX


生產序號 ← LOT NO: Y151130XXXXXXXXXX


標籤識別碼 ← REFERENCE: BTPyyMMddXXXXX
  → QR Code

產地 ← MADE IN XXXXXX

OR

RoHS 標示


EVERLIGHT
5 → 月份

客戶料號 ← CPN: XXXXXXXXXXXX 測試區
  → 安規標示

客戶品名 ← XXXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX


億光料號 ← P/N: XXXXXXXXXXXX

億光品名 ← XXXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX

生產序號 ← LOT NO: Y150516XXX-XXXXXXXXXX-XXXXXXXXXX

包裝數量 ← QTY: 0123456789 HUE: XXXXXXXXXXXX

CTR等級 ← CAT: XXXXXXXXXXXX REF: XXXXXXXXXXXX

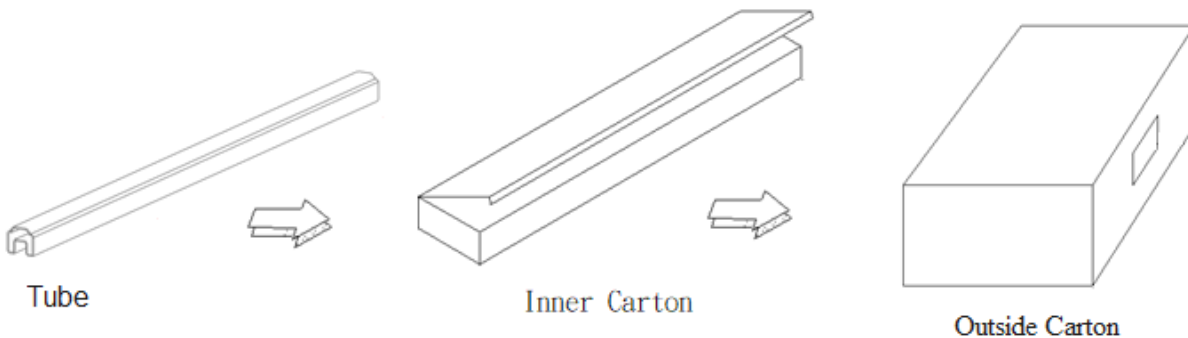
標籤識別碼 ← REFERENCE: BTPYYMMDDXXXXX
  → QR Code

MSL等級 ← MSL-XX MADE IN XXXXXX

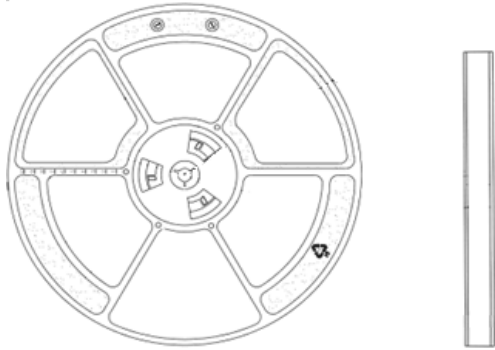
 ↓

 產地

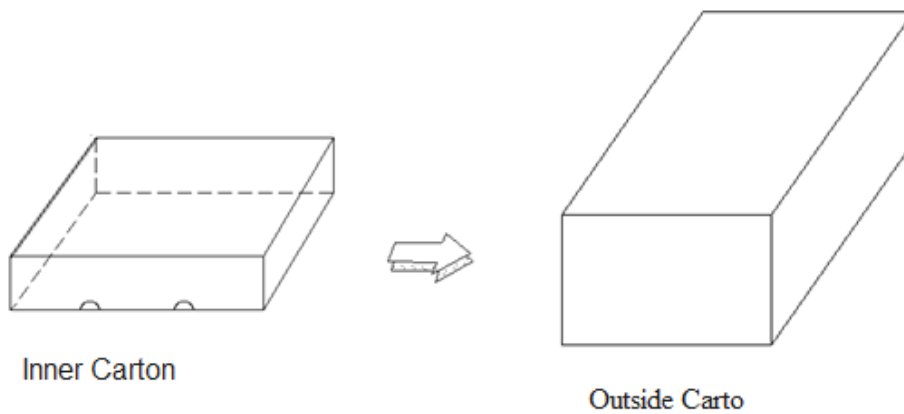
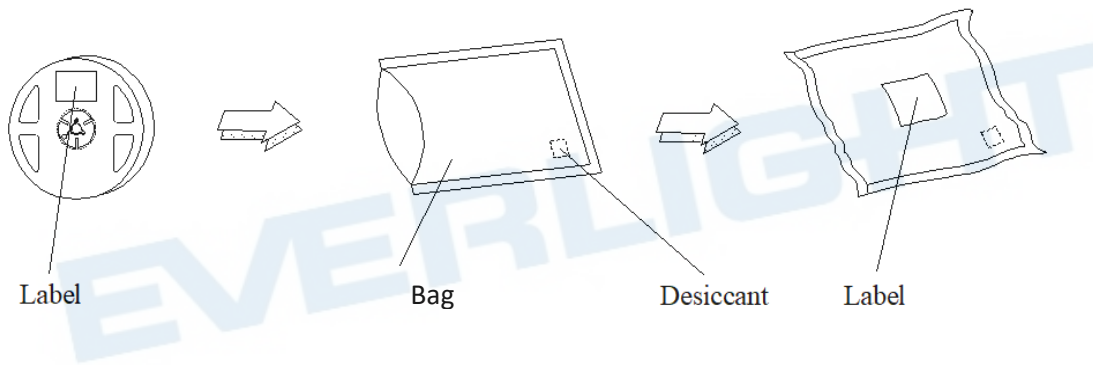
TUBE Dimension



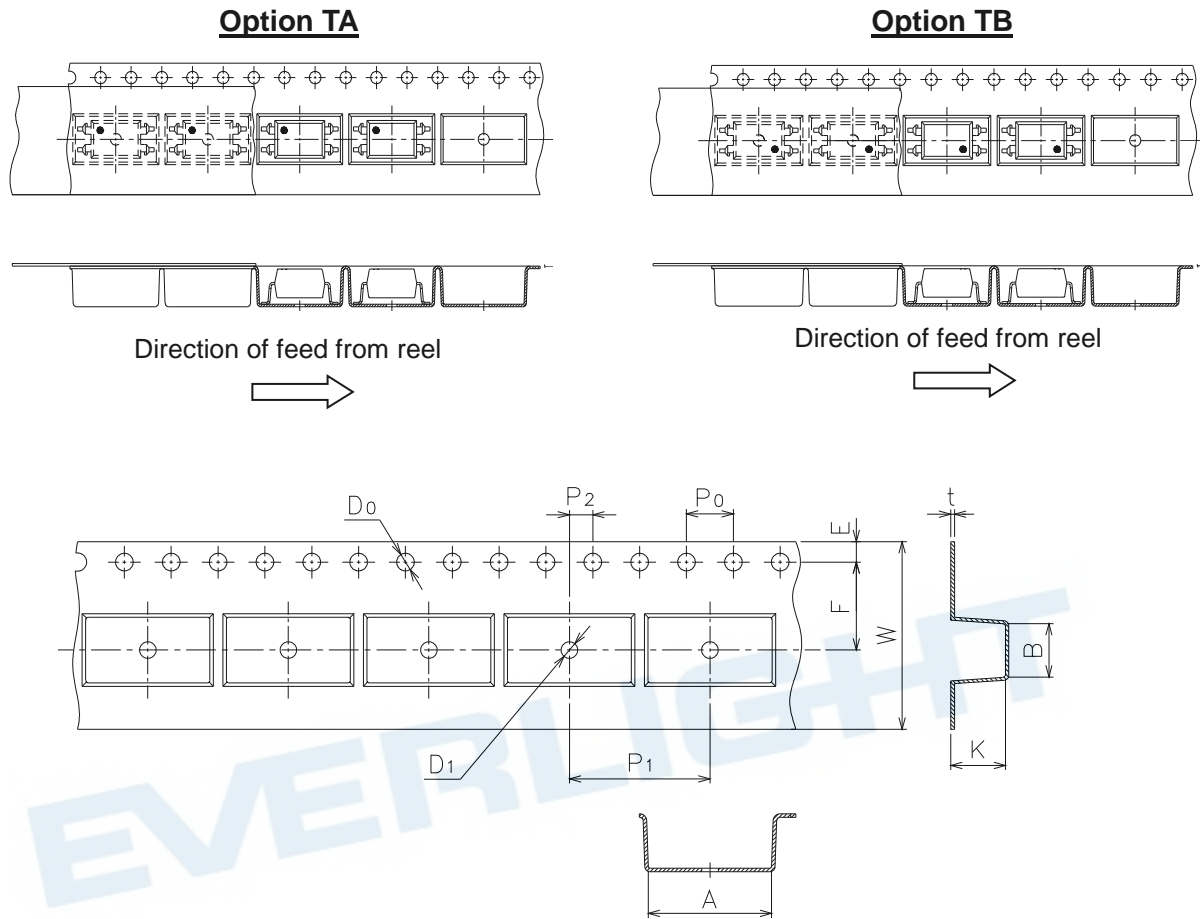
Reel Dimension



Moisture Resistant Packaging

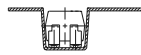
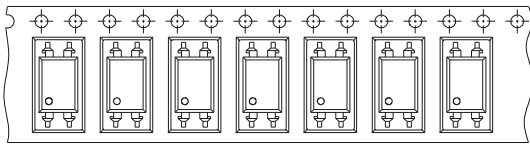


Tape & Reel Packing Specifications

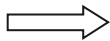


Dimension No.	A	B	Do	D1	E	F
Dimension (mm) S	10.7±0.1	4.65±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension (mm) S1	10.7±0.1	4.65±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension No.	Po	P1	P2	t	W	K
Dimension (mm) S	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0±0.3	4.75±0.1
Dimension (mm) S1	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0±0.3	3.90±0.1

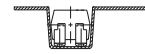
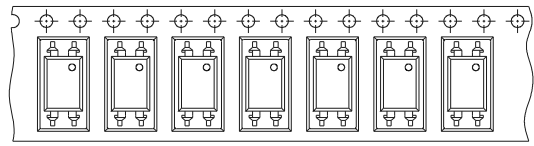
Option TD



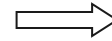
Direction of feed from reel



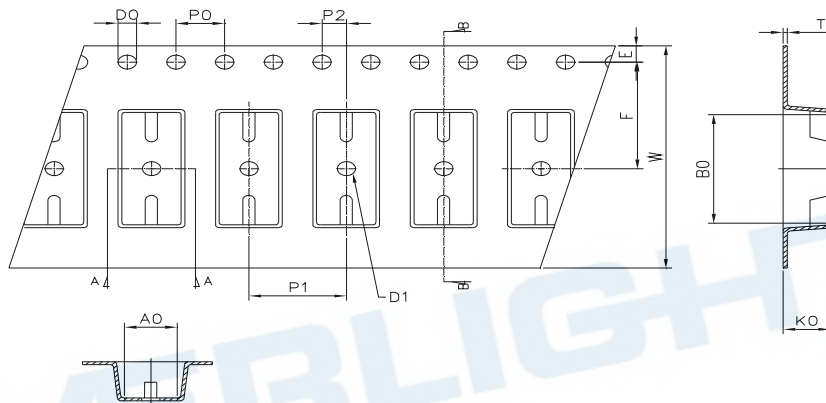
Option TU



Direction of feed from reel



Tape dimensions

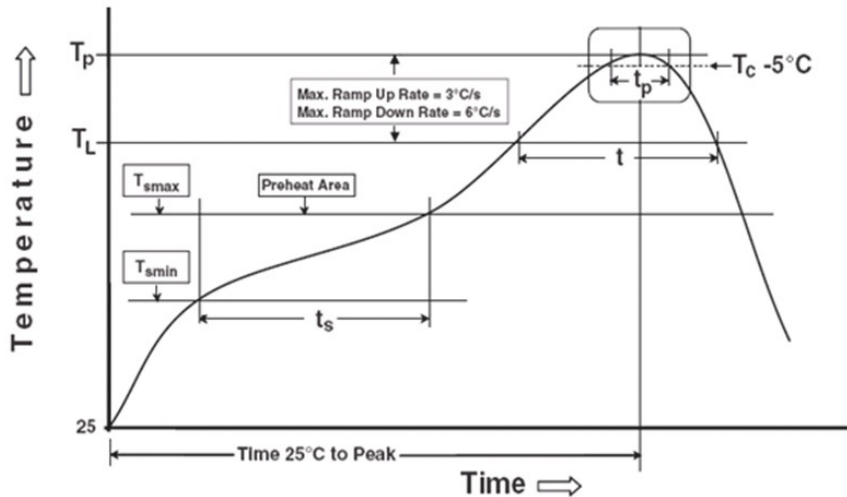


Dimension No.	Ao	Bo	Do	D1	E	F
Dimension (mm) S	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension (mm) S1	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension No.	Po	P1	P2	t	W	Ko
Dimension (mm) S	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	16.00±0.3	4.60±0.1
Dimension (mm) S1	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	16.00±0.3	4.00±0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Notes

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5°C to 35°C and 20 % to 60 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

EVERLIGHT

DISCLAIMER

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
3. These specification sheets include materials protected under copyright of EVERLIGHT corporation. Please don't reproduce or cause anyone to reproduce them without EVERLIGHT's consent.
4. These specification sheets include materials protected under copyright of EVERLIGHT. Reproduction in any form is prohibited without the specific consent of EVERLIGHT.
5. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized Everlight sales agent for special application request.
6. Statements regarding the suitability of products for certain types of applications are based on Everlight's knowledge of typical requirements that are often placed on Everlight products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Everlight's terms and conditions of purchase, including but not limited to the warranty expressed therein.